

ABSTRACT

The present invention relates to a cooling system for use in cooling of semiconductor manufacturing equipment, such as etching equipment. The cooling system (5) includes: at least one heat-exchanging unit (8) configured to generate a cooling liquid for cooling the multiple processing chambers (2A to 2C) arranged in a clean room and supply the cooling liquid to the multiple processing chambers (2A to 2C); a cooling apparatus (10) configured to cool an antifreeze liquid; an antifreeze-liquid circulation line (25) extending between the heat-exchanging unit (8) and the cooling apparatus (10); and an antifreeze-liquid pump (27) configured to circulate the antifreeze liquid, wherein the heat-exchanging unit (8) includes: a cooling-liquid pump (30) configured to circulate the cooling liquid; a heat exchanger (31) configured to perform heat exchange between the cooling liquid and the antifreeze liquid; and a cooling-side buffer tank (33) arranged upstream of the heat exchanger (31) in a circulating direction of the cooling liquid.

FIG. 1